FINAL PROGRAMME

2nd PCNS Passive Components Networking Symposium

September 10-13th 2019, Bucharest, Romania

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Pre-Event Day 10th September 2019

13:00-17:00h Passive Components Mounting Guidelines Workshop

17:00-19:00h Politehnica Bucharest University Tour

Main Conference & Networking Day 11th September 2019

9:00-9:15 Welcome Speech

9:15-10:45 Keynote Presentations; Chairman: Tomas Zednicek; EPCI

- Passive Components Keys to enabling Advanced Future System Designs;
 - Ron Demcko; Technical Sales Group Manager; AVX fellow
- Design Challenges of Capacitors What about downsizing, robustness and energy density for future applications?; Stephan Menzel; Product Development Manager Capacitors; Würth Elektronik eiSos
- Shortage of Products Market Mechanisms and How to avoid Fake-Products; Rüdiger Scheel; VP Automotive, Murata Electronics Europe

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10.45-11.00	Coffee Break	ltelcond

11:00-11:30 Keynote Presentations (cont.); Chairman: Tomas Zednicek; EPCI

• Passive Components – Teaching and Learning;

Paul Svasta, Emeritus Professor; Politehnica University of Bucharest

11:30-13:00h Speakers Introduction and Organisations Flash Presentations

5min flash presentations to introduce speakers, universities and companies and its hot subjects

------ Lunch Break ------

14:00-17:50h Advanced Passive Components Workshop









- 14:00 14:40 Würth Elektronik: How to choose the best Inductor for DC/DC converter and EMI
- 14:40 15:20 KOA Europe: Space saving by high power resistors; Shunt resistor technical notes
- 15:20 16:00 Murata: 3-terminal ceramic capacitors, Common mode choke coils, Ferrite beads

------ Coffee Break ------16:00-16:30 () Itelcond

- 16:30-17:10 AVX: Supercapacitors, ESD protection and multilayer varistors
- 17:10-17:50 Kemet: Tantalum capacitor advances, Commercialisation of space and ceramic capacitors



Panel Discussion & Sessions Day 12th September 2019

9:00-11:00h Hot Topic Panel Discussion MLCC Class II DC BIAS & Ageing Capacitance Loss

tutorial paper and facilitation by: Tomas Zednicek; EPCI

- Manufacturers and end users discussion on definition/reference conditions on MLCC class II capacitors capacitance loss with DC BIAS
- Panelists (Tentative List): AVX, Continental, Kemet, Murata, Valeo

11:00-11:20 ------- Coffee Break ------ Qffee Break ------

11:20-12:20 Session 1 NEW DEVELOPMENT; Chairman: Ron Demcko; AVX Corporation

- 1.1. A Disruptive Nano-laminate Polymer Capacitor Technology for Electric Drive Applications; Angelo Yializis; POlyCharge America Inc; United States
- **1.2.** Integrated and discrete capacitors based on carbon nanostructures with capacitance densities in excess of 200nF/mm²; Sascha Krause; Smoltek AB; Sweden
- 1.3. Advances in Film Resistor Technology; Stephen Oxley; TT Electronics; United Kingdom

12:20-13:20 ------ Lunch Break -----

- 13:20-14:40 Session 2 TECHNOLOGY & ROADMAPS; Chairman: Vlad Bande; TU of Cluj
 - 2.1. Energy Harvesting is not Fiction anymore; Lorandt Fölkel; Würth Elektronik eiSos; Germany
 - 2.2. Analysis of Multi-Layer Ceramic Capacitors used in Power Distribution Networks; Marcel Manofu; Continental; Romania
 - 2.3. Guidelines How to Downsize MLCCs Efficiently; Yuki Nagoshi; Murata; Germany
 - 2.4. Capacitor Trends and Challenges; Martin Barta; TTI; Germany

14:40-15:00 ------ Coffee Break ------ Qitelcond

- 15:00-16:30 Session 3 QUALITY & RELIABILITY; Chairman: Alexander Teverovsky; NASA/GSFC
 - 3.1. COTS procurement for space mission; Denis Lacombe; ESA ESTEC; Netherlands
 - 3.2. Most Reliable, Most Efficient and Price Effective Solid Tantalum Capacitors; Yuri Freeman; Ed Jones; Kemet; USA
 - **3.3.** Real Environment Aluminium Electrolytic Capacitor LifeTime Evaluation and Modelling; Luca Primavesi; ItelCond and Univeristy of Milano; Italy
 - 3.4. Supercapacitor Degradation and Life-time; Vlasta Sedláková; Brno University of Technology; Czech Republic

16:30



Gala Dinner (bus coach to country restaurant)

Sessions Day & Closing 13th September 2019

9:00-10:40 Session 4. MATERIALS & PROCESSES; Chairman: Lorandt Fölkel, Würth Elektronik eiSos

- 4.1. High Bs ferrite material development for high power applications; JC Sun; Bs&T Frankfurt am Main GmbH; Germany
- **4.2. High efficient new Hybrid magnetic EMI filter design for Low Voltage DC distribution**; Thomas Ebel; Wai Keung Mo; Centre for Industrial Electronics, University of Southern Denmark; Denmark
- 4.3. Conductive hybrid threads and their applications; Tomas Blecha; University of West Bohemia; Czech Republic
- 4.4. Tin Whisker or not Whisker; Jean Edmond Le Calvé; Valeo; France
- 4.5. Stable and reliable tantalum supply chain; Roland Chavasse; T.I.C.; Belgium

10:40-11:00 ------ Coffee Break & Sandwiches to Go ------ Qltelcond

11:00-12:00 Session 5. MEASUREMENT & TEST; Chairman: Luca Primavesi; Itelcond

- 5.1. Degradation of ESR in Polymer Tantalum Capacitors during High Temperature Storage; Alexander Teverovsky; NASA/GSFC; United States
- 5.2. Investigation and Experimental Comparison of Magnetic Core Loss for High-Saturation Ferrite Material; Chang Wang; JC Sun; TU of Denmark; Denmark
- 5.3. Evaluation of Active Balancing Circuits for Supercapacitors; Ciprian Ionescu; Politehnica University of Bucharest

12:00-12:20 Best Paper Awards & Closing Ceremony